

# **Material Declaration of Components and Electronic Assemblies: Data Exchange Solutions for Global Environmental Requirements**

---

**August 30/31, 2004**

**Intel - Santa Clara, CA**



# Agenda – Day One

## **8:30 Welcome, Introductions and Agenda/Objectives Overview**

- Todd Brady, Intel
- Jim McElroy, NEMI
- Richard Kubin, NEMI Project Chair/E2open

## **9:00 The Regulatory Environment: An Overview**

- JP Brisson, Allen & Overy

## **9:45 BREAK**

## **10:00 Detailed Review of Industry Declaration Guides**

- EIA/JGPSSI/EICTA Joint Industry Guide – Todd Brady, Intel Worldwide Environmental Health and Safety
- Other Guides – Dieter Bergman, IPC
- WEEE – JB Hollister, JB Hollister Consulting

## **11:00 Material Declaration Exchange Requirements Panel**

- OEM – Butch Morel, Lucent; Diane Fisher, HP; Nancy Bolinger, IBM
- EMS – Ron D’Hondt, Celestica; Eric Austerman, Jabil
- Component Supplier / Manufacturer – Mark Frimann, TI; Joel Sherman, KEMET
- Bare Board Supplier – Dana Korf, Sanmina-SCI

## **12:30 Working Lunch: Break-out Groups on Requirements Definition**



# Agenda – Day One

## **2:00 Break-out Reports**

## **2:15 Emerging Solutions Panel**

- RosettaNet Solutions – John Cartwright, RosettaNet
- Product Data eXchange: Integrating Material Declaration into the BOM Structure – Barbara Goldstein, NIST; Dries D’hooghe, Agile Software
- International Component Dictionary Description (IEC / ISO) – Dieter Bergman, IPC

## **3:45 Break**

## **4:00 Strategy & Architecture for Standards-based Message Exchange**

- Automated Enablement Infrastructure – John Cartwright, Intel
- Multiple Messaging– Mark Schenecker, E2open

## **4:45 Commercial Solutions**

- Solution providers are invited to present a 5-minute perspective on their support for standardized data exchange and their market readiness for MCD solutions
- Agile Software                      - E2open                      - i2
- Oracle                                      - PTC                                      - SAP
- Synapsis                                      - Total Parts Plus

## **5:45 Adjourn**

## **6:30 Group Dinner**



# Agenda – Day Two

- 8:30 Review of previous day highlights, Day Two agenda**
- 8:45 Lessons Learned from Early Material Exchange Implementations**
- Japanese Green Procurement Implementation – Mr Yamaguchi, Fuji (Webcast)
  - NEMI Material Declaration Team Phase 1 Results – Nancy Bolinger, IBM
  - Automotive End-of-Life Vehicle Directive – Chris Harden, MDSMap
  - RosettaNet Implementation – Mike Young, Agilent
  - Data Sheet Implementation – Kara Thompson, Dell; Marissa Yao, Intel
- 10:45 Break**
- 11:00 Material Composition Declaration Data Exchange Roadmap**
- Format Solutions Matrix Overview – Richard Kubin, E2open
  - Process Flow Overview – JB Hollister, JB Hollister Consulting
  - Strategies, Next Steps, Resources
- 12:30 Working Lunch: Project Team Next Steps**
- PDX Development
  - RosettaNet
  - Pilot Demonstrations
- 3:30 Wrap-up and Adjourn**
- 4:00 Intel Museum Tour**



# Workshop Objectives

- Understand the reporting requirements for both RoHS and WEEE.
- Understand the requirements for material composition data at each level in the supply chain, including components and assembly processes.
- Understand current and proposed solutions and the role of data exchange standards, including IPC PDX and RosettaNet.
- Help participating companies and organizations understand the data interchange landscape, and current best practices and future directions, from both a process and IT perspective.
- Understand IT infrastructure requirements, both internal and external.
- Reach consensus on a matrix of data exchange requirements for compliance to materials declaration regulations.
- Help develop a "roadmap" for driving industry standards development and adoption.
- Provide companies with information to support their internal MCD compliance roadmaps.
- Provide relevant standards bodies with user input to drive continuous improvement and coordination, including establishing priorities and a workplan for the delivery of Version 2.0 of the IPC Product Data eXchange (PDX) standard to support MCD compliance.
- Provide standards bodies requirements needed to develop MCD exchange standards which support as-built composition, as-designed material requirements, recycling, and take back.
- Provide solution providers with insight on emerging data exchange formats, and how to meet future customer exchange needs.




# Potentially Relevant Standards & Guidelines

- **Joint Industry Guide** - Material Composition Declaration Guide
- **ECMA Technical Report TR/70** - Product-related environmental attributes (Section 5.8)
- **EN 45014** General criteria for suppliers declaration of conformance
- **IEC 61906**: Procedure for declaration of materials in products of the electrotechnical and electronics industry (DIN 19220)
- **ISO 14021**: Environmental labels and declarations - Self-declaration environmental claims - Guidelines and definition and usage of terms
- **ZVEI** Information on Substances and Materials in Products (Umbrella Spec)
- **JEDEC / IPC J-STD-020C**: Moisture/Reflow Sensitivity Classification
- **JEDEC / IPC J-STD-033A**: Handling, Packing, Shipping and use of Moisture/Reflow Sensitive SMDs
- **JEDEC JESD97**: Marking, Symbols, and Labels for Identification of Lead (Pb) Free Assemblies, Components, and Devices
- **IPC-1065 (1401)**: Material Declaration Handbook (For Users and Manufacturers of Printed Circuit Boards)
- **JGPSSI**: Excel-based worksheet for Material Declaration
- **Centor Compliance Connect**: Excel-based worksheet for Material Declaration
- **IPC-PDX 2.0**: Supply Chain Communication
- **RosettaNet PIP 2A9/2A10**: Query/Distribute Technical/Engineering Information
- **RosettaNet PIP 2A13**: Distribute Material Composition Information
- **ECALGA**: ebXML standard for exchange of engineering data under development by JEITA



# Potentially Relevant Standards & Guidelines - Material/Component Content

|                | Design   | Manufacturing | Logistics | End-of-Life |
|----------------|--|---------------|-----------|-------------|
| Bulk Materials |  |               |           |             |
| Components     |  |               |           |             |
| PCBs           |  |               |           |             |
| Sub-assemblies |  |               |           |             |
| PCBAs          |  |               |           |             |
| Products       |  |               |           |             |
|                |  |               | ?         | ?           |



# Potentially Relevant Standards & Guidelines - Material/Component Data Exchange

|                | Design | Manufacturing | Logistics | End-of-Life |
|----------------|--------|---------------|-----------|-------------|
| Bulk Materials |        |               |           |             |
| Components     |        |               |           |             |
| PCBs           |        |               |           |             |
| Sub-assemblies |        |               |           |             |
| PCBAs          |        |               |           |             |
| Products       |        |               |           |             |
|                |        |               |           |             |